ABSTRACT

INTEGRATED CIRCUIT PACKAGE WITH DIFFERENT HARDNESS BUMP PAD AND BUMP AND MANUFACTURING METHOD THEREFOR

A manufacturing method for an integrated circuit package is provided including forming a contact pad under a passivation layer on an integrated circuit, forming an opening in the passivation layer exposing the contact pad, and forming an under bump metallurgy over the contact pad and the passivation layer. The method further includes forming a bump pad over the under bump metallurgy of a material having a first hardness and forming a bump on and over the bump pad, the bump having a top flat surface and of a material having a second hardness softer than the first hardness. (Fig. 6)